REVISIONS			
LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED

PRELIMINARY (5/22/09) – FOR INFORMATION ONLY

NOT TO BE USED FOR PROCUREMENT

REV																				
SHEET																				
REV																				
SHEET	15	16	17	18	19	20	21	22												
REV STATUS			REV																	
OF SHEETS			SHEET			1	2	3	4	5	6	7	8	9	10	11	12	13	14	

PMIC N/A

PREPARED BY

CHECKED BY

APPROVED BY

DRAWING APPROVAL DATE

REVISION LEVEL

STANDARD MICROCIRCUIT DRAWING

THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE

AMSC N/A

DEFENSE SUPPLY CENTER COLUMBUS
COLUMBUS, OHIO 43218-3990
http://www.dscc.dla.mil

MICROCIRCUIT, MEMORY, DIGITAL, 512K X 36 SYNCHRONOUS STATIC RANDOM ACCESS MEMORY (SRAM), 2.5 V, MONOLITHIC SILICON

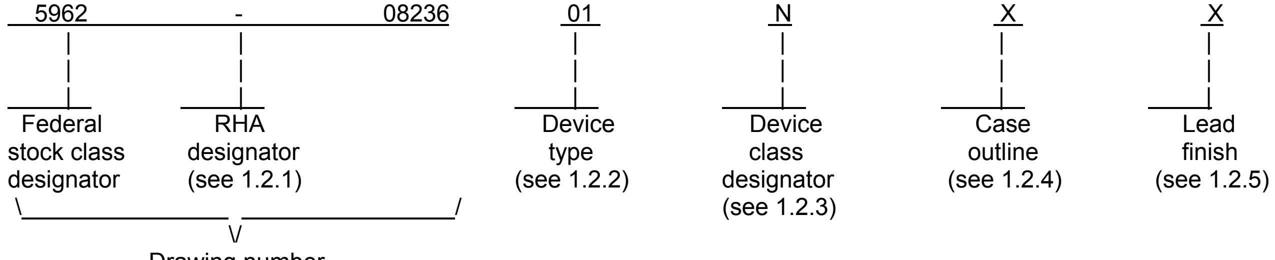
SIZE	CAGE CODE	
A	**67268**	**5962-08236**

SHEET 1 OF 24

1. SCOPE

1.1 Scope. This drawing documents three product assurance class levels consisting of high reliability (device class Q), space application (device class V) and nontraditional performance environment (device class N). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels are reflected in the PIN.

1.2 PIN. The PIN is as shown in the following example:



1.2.1 RHA designator. Device classes N, Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 Device type(s). The device type(s) identify the circuit function as follows:

Device type	Generic number 1/	Circuit function	Maximum operating speed
01		128K X 32 CMOS SRAM	250 MHz
02		128K X 32 CMOS SRAM	200 MHz
03		128K X 32 CMOS SRAM	167 MHz

1.2.3 Device class designator. The device class designator is a single letter identifying the product assurance level as follows:

Device class	Device requirements documentation
N	Certification and qualification to MIL-PRF-38535 for plastic encapsulated microcircuit (PEM)
Q or V	Certification and qualification to MIL-PRF-38535

1.2.4 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	Terminals	Package style
X	See figure 1	100	Thin quad flat pack (TQFP)
Y	See figure 1	119	Plastic ball grid array (PBGA)
Z	See figure 1	165	Fine pitch ball grid array (FBGA)

1.2.5 Lead finish. The lead finish is as specified in MIL-PRF-38535 for device classes N, Q and V.

1/ Generic numbers are listed on the Standard Microcircuit Drawing Source Approval Bulletin at the end of this document and will also be listed in MIL-HDBK-103 (see 6.6.2 herein).

1.3 Absolute maximum ratings. 2/

Supply voltage range (V_{DD})	-0.5 V dc to + 3.6 V dc
Voltage range on any input	-0.5 V dc to V_{DD} + 0.5 V dc
Voltage range on any output pin	-0.5 V dc to V_{DDQ} + 0.5 V dc
Storage temperature range	-65°C to +150°C
Maximum power dissipation (P_D)	
01	1.26 W
02	1.08 W
03	0.99 W
Lead temperature (soldering, 10 seconds)	+260°C
Thermal resistance, junction-to-case (Θ_{JC}):	
Case X	4.08 °C/W 3/
Case Y	6.2 °C/W 3/
Case Z	4.0 °C/W 3/
Junction temperature (T_J)	+140°C 4/
Output current	20 mA

1.4 Recommended operating conditions.

Supply voltage range (V_{DD})	2.375 V dc to 2.625 V dc
Supply voltage to outputs (V_{DDQ})	2.375 V dc to V_{DD}
Supply voltage (V_{SS})	0 V
Input high voltage range (V_{IH})	1.7 V dc to V_{DD} + 0.3 V dc 5/
Input low voltage range (V_{IL})	-0.3 V dc to 0.7 V dc 5/
Case operating temperature range (T_C)	-55°C to +125°C

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.
MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.
MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at http://assist.daps.dla.mil/quicksearch/ or http://assist.daps.dla.mil or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Non-Government publications. The following document(s) form a part of this document to the extent specified herein. Unless otherwise specified, the issues of the documents are the issues of the documents cited in the solicitation.

AMERICAN SOCIETY FOR TESTING AND MATERIALS (ASTM)

2/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

3/ Tested initially and after any design or process changes that may affect these parameters.

4/ Maximum junction temperature shall not be exceeded except for allowable short duration burn-in screening conditions in accordance with method 5004 of MIL-STD-883.

5/ Overshoot: V_{IH}(AC) < V_{DDQ} +1.5V (Pulse width less than t_{CYC}/2), Undershoot: V_{IL}(AC) > -2V (Pulse width less than t_{CYC}/2).

ASTM Standard F1192-95 - Standard Guide for the Measurement of Single Event Phenomena from Heavy Ion Irradiation of Semiconductor Devices.

(Applications for copies of ASTM publications should be addressed to: ASTM International, PO Box C700, 100 Barr Harbor Drive, West Conshohocken, PA 19428-2959; http://www.astm.org.)

ELECTRONICS INDUSTRIES ASSOCIATION (EIA)

JEDEC Standard EIA/JESD78 -	IC Latch-Up Test.
JEDEC Solid State Product Outline MS-026 -	Low/Thin Profile Plastic Quad Flat Package, 2.00 mm Footprint, Optional Heat Slug
JEDEC Solid State Product Outline MO-216 -	Thin Profile, Square and Rectangular, Ball Grid Array Family, 1.00 & 0.80MM Pitches.

(Applications for copies should be addressed to the Electronics Industries Association, 2500 Wilson Boulevard, Arlington, VA 22201; http://www.jedec.org.)

(Non-Government standards and other publications are normally available from the organizations that prepare or distribute the documents. These documents also may be available in or through libraries or other informational services.)

2.3 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements for device classes N, Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes N, Q and V.

3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein and figure 1.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 2.

3.2.3 Truth table(s). The truth table(s) shall be as specified on figure 3.

3.2.4 Functional tests. Various functional tests are used to test this device. If the test patterns cannot be implemented due to test equipment limitations, alternate test patterns to accomplish the same results shall be allowed. For device classes N, Q and V alternate test patterns shall be under the control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the preparing or acquiring activity upon request.

3.3 Electrical performance characteristics and postirradiation parameter limits. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full case operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table IIA. The electrical tests for each subgroup are defined in table I.

3.5 Marking. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes N, Q and V shall be in accordance with MIL-PRF-38535

3.5.1 Certification/compliance mark. The certification mark for device classes N, Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535.

3.6 Certificate of compliance. For device classes N, Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes N, Q and V, the requirements of MIL-PRF-38535.

3.7 Certificate of conformance. A certificate of conformance as required for device classes N, Q and V in MIL-PRF-38535 shall be provided with each lot of microcircuits delivered to this drawing.

TABLE I. Electrical performance characteristics

Test	Symbol	Conditions $-55° \le T_C \le 125°C$ $2.375\ V \le V_{DD} \le 2.625\ V$ $2.375\ V \le V_{DDQ} \le V_{DD}$ Unless Otherwise Specified 2/ 3/		Group A Subgroups	Device Type	Limits		Units
						Min	Max	
Output HIGH Voltage	V_{OH}	I_{OH} = -1.0 mA		1, 2, 3	All	2.0	---	V
Output LOW Voltage	V_{OL}	I_{OL} = 1.0 mA		1, 2, 3	All	---	0.4	V
Input HIGH Voltage	V_{IH}			1, 2, 3	All	1.7	V_{DD} + 0.3 V	V
Input LOW Voltage	V_{IL}			1, 2, 3	All	-0.3	0.7	V
Input Leakage Current	I_X	Input Leakage Current except ZZ and MODE	GND $\le V_I \le V_{DDQ}$	1, 2, 3	All	-5	5	uA
		Input Current of MODE	Input = V_{SS}			-30	---	
			Input = V_{DD}			---	5	
		Input Current of ZZ	Input = V_{SS}			-5	---	
			Input = V_{DD}			---	30	
Output Leakage Current	I_{OZ}	GND $\le V_I \le V_{DDQ}$, output disabled		1, 2, 3	All	-5	5	uA
V_{DD} Operating Supply Current	I_{DD}	V_{DD} = max, I_{OUT}=0 mA f = f_{MAX} = $1/t_{CYC}$	4-ns cycle, 250 MHz	1, 2, 3	01	---	350	mA
			5-ns cycle, 200 MHz		02	---	300	
			6-ns cycle, 167 MHz		03	---	275	
Automatic CE Power-Down Current - TTL Inputs	I_{SB1}	V_{DD} = max, device deselected, $V_{IN} \ge V_{IH}$ or $V_{IN} \le V_{IL}$ f = f_{MAX} =$1/t_{CYC}$	4-ns cycle, 250 MHz	1, 2, 3	01	---	160	mA
			5-ns cycle, 200 MHz		02	---	150	mA
			6-ns cycle, 167 MHz		03	---	140	mA
Automatic CE Power-Down Current - CMOS Inputs	I_{SB2}	V_{DD} = max, device deselected, $V_{IN} \le 0.3V$ or $V_{IN} \ge V_{DDQ} - 0.3V$, f = 0	All speeds	1, 2, 3	All	---	70	mA
Automatic CE Power-Down Current - CMOS Inputs	I_{SB3}	V_{DD} = max, device deselected or $V_{IN} \le 0.3V$ or $V_{IN} \ge V_{DDQ} - 0.3V$, f = f_{MAX} =$1/t_{CYC}$	4-ns cycle, 250 MHz	1, 2, 3	01	---	135	mA
			5-ns cycle, 200 MHz		02	---	130	
			6-ns cycle, 167MHz		03	---	125	

See footnotes at end of table.

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions $-55° \le T_C \le 125°C$ $2.375\ V \le V_{DD} \le 2.625\ V$ $2.375\ V \le V_{DDQ} \le V_{DD}$ Unless Otherwise Specified 2/ 3/		Group A Subgroups	Device Type	Limits		Units
						Min	Min	
Automatic CE Power-Down Current - TTL Inputs	I_{SB4}	V_{DD} = max, device deselected, $V_{IN} \ge V_{IH}$ or $V_{IN} \le V_{IL}$, f = 0	All speeds	1, 2, 3	All		80	mA
Snooze Mode Standby current	I_{DDZZ}	$ZZ \ge V_{DD} - 0.2V$		1, 2, 3	All		80	mA
Input Capacitance 1/	C_{IN}	T_A = 25°C, f = 1 MHz, V_{DD} = 2.5V V_{DDQ} = 2.5V	Case X	4	All		5	pF
			Case Y				8	
			Case Z				9	
Clock Input Capacitance 1/	C_{CLK}		Case X	4	All		5	pF
			Case Y				8	
			Case Z				9	
Input/Output Capacitance 1/	$C_{I/O}$		Case X	4	All		5	pF
			Case Y				8	
			Case Z				9	

See footnotes at end of table.

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions $-55° \leq T_C \leq 125°C$ $2.375 V \leq V_{DD} \leq 2.625 V$ $2.375 V \leq V_{DDQ} \leq V_{DD}$ Unless Otherwise Specified 2/ 3/	Group A Subgroups	Device Type	Limits Min	Limits Max	Units
Clock Cycle Time	t_{CYC}	See Figure 5 as applicable. 4/ 8/ 9/	9, 10, 11	01	4.0	---	ns
				02	5.0	---	
				03	6.0	---	
Clock HIGH	t_{CH}		9, 10, 11	01	1.7	---	ns
				02	2.0	---	
				03	2.2	---	
Clock LOW	t_{CL}		9, 10, 11	01	1.7	---	ns
				02	2.0	---	
				03	2.2	---	
Data Output valid after CLK rise	t_{CO}		9, 10, 11	01	---	2.6	ns
				02	---	3.0	
				03	---	3.4	
Data Output hold after CLK rise	t_{DOH}		9, 10, 11	01	1.0	---	ns
				02	1.3	---	
				03	1.3	---	
Clock to Low-Z 5/ 6/ 7/	t_{CLZ}		9, 10, 11	01	1.0	---	ns
				02	1.3	---	
				03	1.3	---	
Clock to High-Z 5/ 6/ 7/	t_{CHZ}		9, 10, 11	01	---	2.6	ns
				02	---	3.0	
				03	---	3.4	
$\overline{OE}$ Low to Output valid	t_{OEV}		9, 10, 11	01	---	2.6	ns
				02	---	3.0	
				03	---	3.4	
$\overline{OE}$ Low to Output Low-Z 5/ 6/ 7/	t_{OELZ}		9, 10, 11	01	0	---	ns
				02	0	---	
				03	0	---	
$\overline{OE}$ High to Output High-Z 5/ 6/ 7/	t_{OEHZ}		9, 10, 11	01	---	2.6	ns
				02	---	3.0	
				03	---	3.4	
Address setup before CLK rise	t_{AS}		9, 10, 11	01	1.2	---	ns
				02	1.4	---	
				03	1.5	---	
Data Input Setup before CLK rise	t_{DS}		9, 10, 11	01	1.2	---	ns
				02	1.4	---	
				03	1.5	---	
$\overline{CEN}$ setup before CLK rise	t_{CENS}		9, 10, 11	01	1.2	---	ns
				02	1.4	---	
				03	1.5	---	
$\overline{WE}$, $\overline{BW_X}$ Setup before CLK rise	t_{WES}		9, 10, 11	01	1.2	---	ns
				02	1.4	---	
				03	1.5	---	
ADV/$\overline{LD}$, setup before CLK rise	t_{ALS}		9, 10, 11	01	1.2	---	ns
				02	1.4	---	
				03	1.5	---	

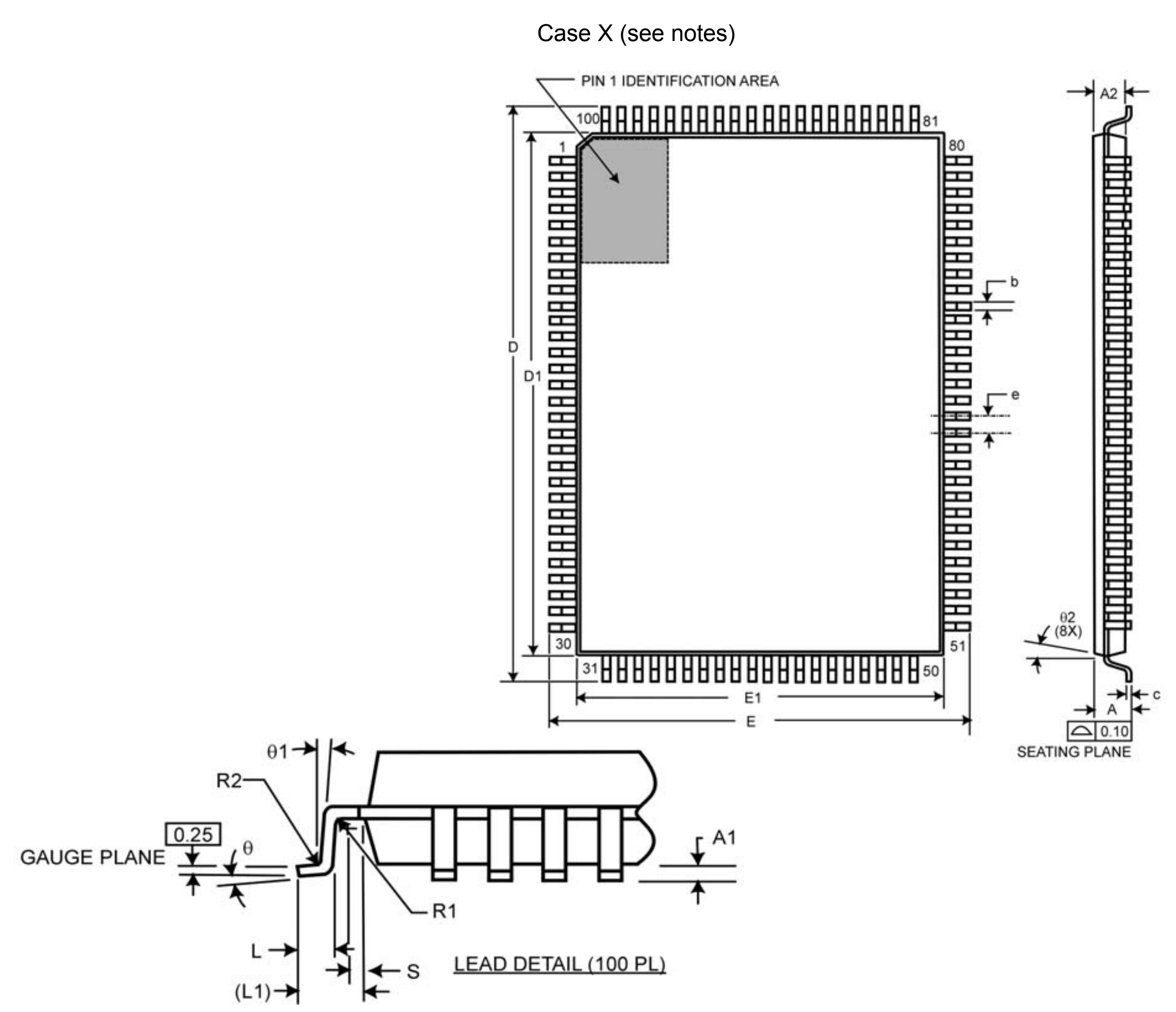
See footnotes at end of table.

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions $-55° \leq T_C \leq 125°C$ $2.375 V \leq V_{DD} \leq 2.625V$ $2.375 V \leq V_{DDQ} \leq V_{DD}$ Unless Otherwise Specified 2/ 3/	Group A Subgroups	Device Type	Limits		Units
					Min	Max	
Chip Enable setup before CLK rise	t_{CES}	See Figure 5 as applicable. 4/ 8/ 9/	9, 10, 11	01	1.2	---	ns
				02	1.4	---	
				03	1.5	---	
Address Hold after CLK rise	t_{AH}		9, 10, 11	01	0.3	---	ns
				02	0.4	---	
				03	0.5	---	
Data Input hold after CLK rise	t_{DH}		9, 10, 11	01	0.3	---	ns
				02	0.4	---	
				03	0.5	---	
$\overline{CEN}$ hold after CLK rise	t_{CENH}		9, 10, 11	01	0.3	---	
				02	0.4	---	
				03	0.5	---	ns
$\overline{WE}$, $\overline{BW}_X$ hold after CLK rise	t_{WEH}		9, 10, 11	01	0.3	---	
				02	0.4	---	
				03	0.5	---	ns
ADV/$\overline{LD}$ hold after CLK rise	t_{ALH}		9, 10, 11	01	0.3	---	
				02	0.4	---	
				03	0.5	---	ns
Chip Enable hold after CLK rise	t_{CEH}		9, 10, 11	01	0.3	---	
				02	0.4	---	
				03	0.5	---	ns
Device Operation to ZZ	t_{ZZS}	$ZZ \geq V_{DD} - 0.2V$	9, 10, 11	All	---	$2t_{CYC}$	ns
ZZ recovery time	t_{ZZREC}	$ZZ \leq 0.2V$	9, 10, 11	All	$2t_{CYC}$	---	ns
ZZ active to snooze current 7/	t_{ZZI}		9, 10, 11	All	---	$2t_{CYC}$	ns
ZZ inactive to exit snooze current 7/	t_{RZZI}		9, 10, 11	All	0	---	ns

1/ Tested initially and after any design or process changes that may affect these parameters.
2/ All voltage referenced to ground.
3/ Overshoot: $V_{IH}(AC) < V_{DDQ} + 1.5V$ (Pulse width less than $t_{CYC}/2$), Undershoot: $V_{IL}(AC) > -2$ (Pulse width less than $t_{CYC}/2$).
4/ Power up: Assumes a linear ramp from 0V to $V_{DD}(min)$ within 200 ms. During this time, $V_{IH} < V_{DD}$ and $V_{DDQ} \leq V_{DD}$.
5/ t_{CHZ}, t_{CLZ}, t_{OELZ}, and t_{OEHZ} are specified with AC test conditions shown in Figure 4 (b), AC Test Loads. Transition is measured ± 200 mV from steady-state voltage.
6/ At any given voltage and temperature , t_{OEHZ} is less than t_{OELZ} and t_{CHZ} is less than t_{CLZ} to eliminate bus contention between SRAMs when sharing the same data bus. These specifications do not imply a bus contention condition, but reflect parameters guaranteed over worst case user conditions. Device is designed to achieve High-Z prior to Low-Z under the same system conditions.
7/ This parameter is sampled and not 100% tested.
8/ Timing reference level is 1.25V when $V_{DDQ} = 2.5V$.
9/ Test conditions shown in figure 4 (a), AC Test Loads unless otherwise noted.

Case X (see notes)

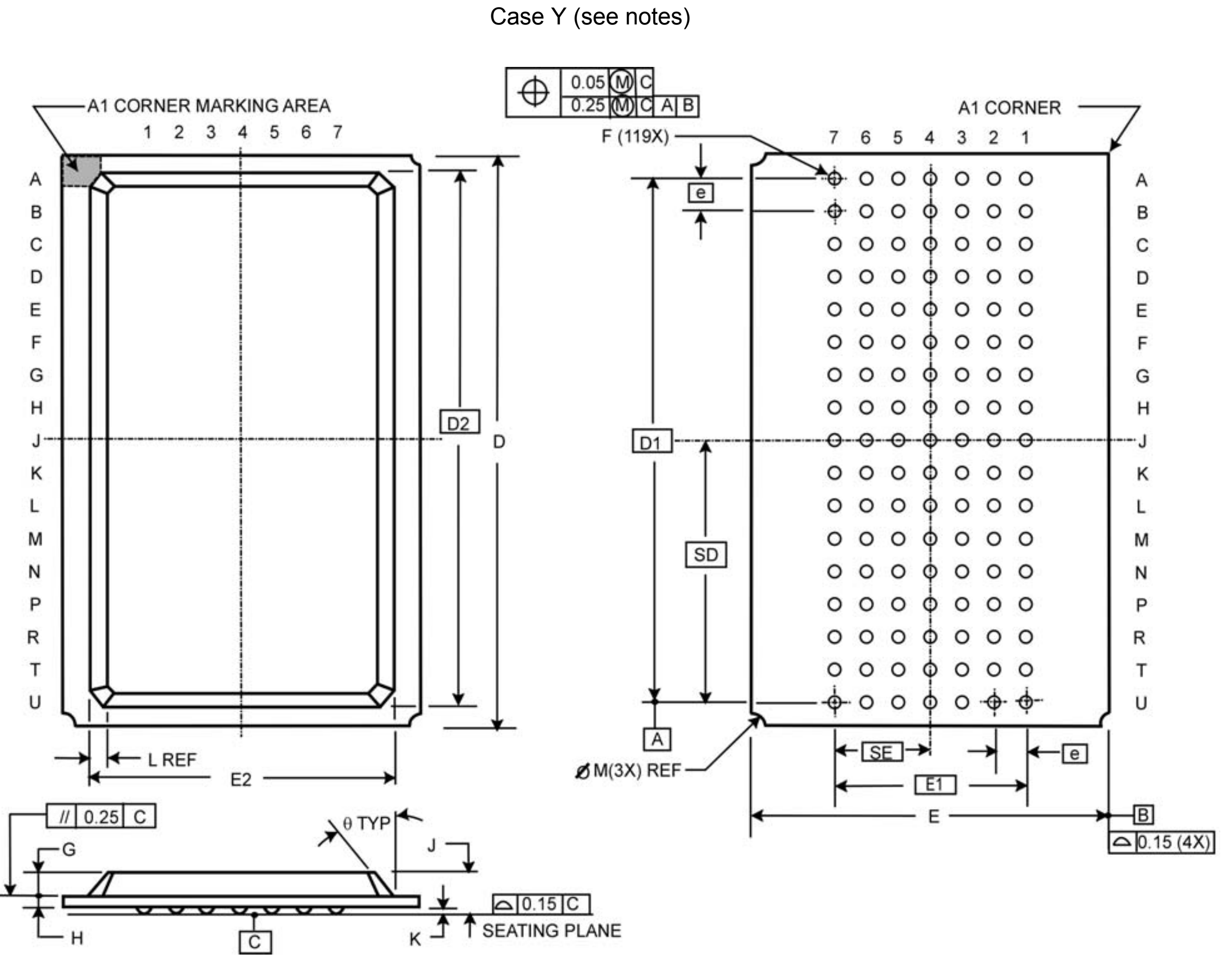


Symbol	Millimeters			Symbol	Millimeters		
	Min	Nom	Max		Min	Nom	Max
A	---	---	1.60	e	---	0.65	---
A1	0.05	---	0.15	L	0.45	0.60	0.75
A2	1.35	1.40	1.45	L1	---	1.00	---
b	0.22	0.30	0.38	R1	0.08	---	0.20
c	---	---	0.20	R2	0.08	---	0.20
D	21.80	22.00	22.20	θ	0˚	---	7˚
D1	19.90	20.00	20.10	θ1	0˚	---	---
E	15.80	16.00	16.20	θ2	11˚	12˚	13˚
E1	13.90	14.00	14.10	N	100		

NOTES:
1. Index area: a notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the area shown. The manufacturer's identification shall not be used as pin one identification mark.
2. Ref: JEDEC MS-026 (BHA)

Figure 1. Case outlines.

Case Y (see notes)



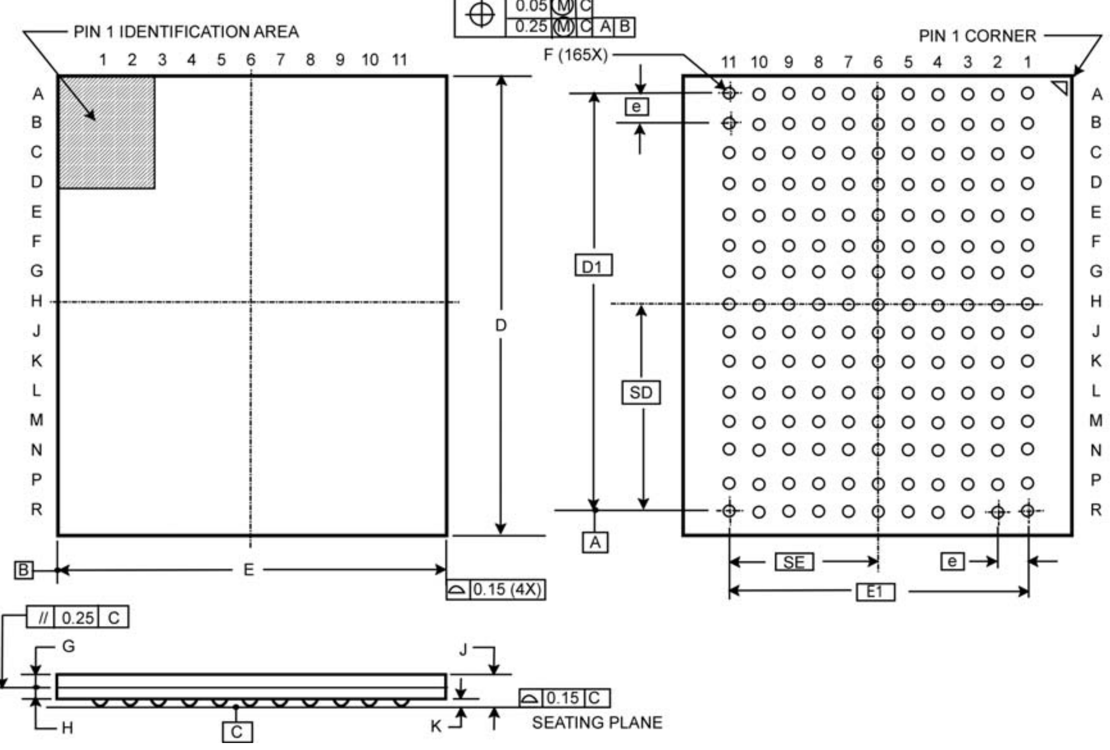
Symbol	Millimeters			Symbol	Millimeters		
	Min	Nom	Max		Min	Nom	Max
D	21.80	22.00	22.20	H	0.51	0.56	0.61
D1	---	20.32	---	J	---	---	2.40
D2	---	19.50	---	K	0.50	0.60	0.70
E	13.80	14.00	14.20	L	---	0.70	---
E1	---	7.62	---	M	---	1.00	---
E2	---	12.00	---	SD	---	10.16	---
e	---	1.27	---	SE	---	3.81	---
F	0.60	0.75	0.90	θ	---	30˚	---
G	0.85	0.90	0.95	N	119		

NOTES:

1. Index area: a notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the area shown. The manufacturer's identification shall not be used as pin one identification mark.

Figure 1. Case outlines.- continued

Case Z (see notes)



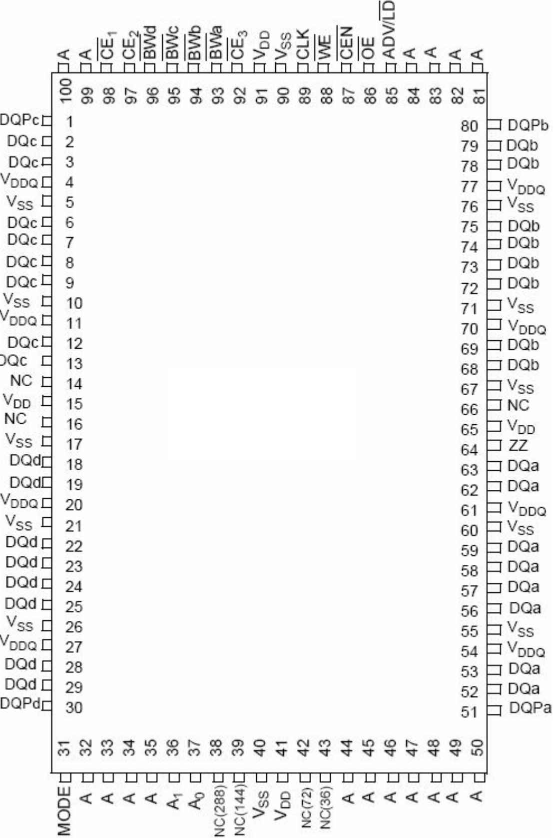
Symbol	Millimeters			Symbol	Millimeters		
	Min	Nom	Max		Min	Nom	Max
D	14.90	15.00	15.10	H	0.31	0.36	0.41
D1	---	14.00 BSC	---	J	---	---	1.40
E	12.90	13.00	13.10	K	0.29	0.35	0.41
E1	---	10.00 BSC	---	SD	---	7.00 BSC	---
e	---	1.00 BSC	---	SE	---	5.00 BSC	---
f	0.44	0.50	0.64	N	165		
g	0.48	0.53	0.58				
D	14.90	15.00	15.10				

NOTES:

1. Index area: a notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the area shown. The manufacturer's identification shall not be used as pin one identification mark.
2. Ref: JEDEC MO-216 for ball pattern.

Figure 1. Case outlines.- continued

Case X (100 TQFP)



Case Y (119 BGA)

	1	2	3	4	5	6	7
A	V_{DDQ}	A	A	A	A	A	V_{DDQ}
B	NC/576M	CE_2	A	ADV/$\overline{LD}$	A	$\overline{CE}_3$	NC
C	NC/1G	A	A	V_{DD}	A	A	NC
D	DQ_C	DQP_C	V_{SS}	NC	V_{SS}	DQP_B	DQ_B
E	DQ_C	DQ_C	V_{SS}	$\overline{CE}_1$	V_{SS}	DQ_B	DQ_B
F	V_{DDQ}	DQ_C	V_{SS}	$\overline{OE}$	V_{SS}	DQ_B	V_{DDQ}
G	DQ_C	DQ_C	$\overline{BW}_C$	A	$\overline{BW}_B$	DQ_B	DQ_B
H	DQ_C	DQ_C	V_{SS}	$\overline{WE}$	V_{SS}	DQ_B	DQ_B
J	V_{DDQ}	V_{DD}	NC	V_{DD}	NC	V_{DD}	V_{DDQ}
K	DQ_D	DQ_D	V_{SS}	CLK	V_{SS}	DQ_A	DQ_A
L	DQ_D	DQ_D	$\overline{BW}_D$	NC	$\overline{BW}_A$	DQ_A	DQ_A
M	V_{DDQ}	DQ_D	V_{SS}	$\overline{CEN}$	V_{SS}	DQ_A	V_{DDQ}
N	DQ_D	DQ_D	V_{SS}	A1	V_{SS}	DQ_A	DQ_A
P	DQ_D	DQP_D	V_{SS}	A0	V_{SS}	DQP_A	DQ_A
R	NC/144M	A	MODE	V_{DD}	NC	A	NC/288M
T	NC	NC/72M	A	A	A	NC/36M	ZZ
U	V_{DDQ}	TMS	TDI	TCK	TDO	NC	V_{DDQ}

Figure 2. Terminal connections.

Case Z (165 FBGA)

	1	2	3	4	5	6	7	8	9	10	11
A	NC/576M	A	$\overline{CE}_1$	$\overline{BW}_C$	$\overline{BW}_B$	$\overline{CE}_3$	$\overline{CEN}$	ADV/$\overline{LD}$	A	A	NC
B	NC/1G	A	CE_2	$\overline{BW}_D$	$\overline{BW}_A$	CLK	$\overline{WE}$	$\overline{OE}$	A	A	NC
C	DQP_C	NC	V_{DDQ}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{DDQ}	NC	DQP_B
D	DQ_C	DQ_C	V_{DDQ}	V_{DD}	V_{SS}	V_{SS}	V_{SS}	V_{DD}	V_{DDQ}	DQ_B	DQ_B
E	DQ_C	DQ_C	V_{DDQ}	V_{DD}	V_{SS}	V_{SS}	V_{SS}	V_{DD}	V_{DDQ}	DQ_B	DQ_B
F	DQ_C	DQ_C	V_{DDQ}	V_{DD}	V_{SS}	V_{SS}	V_{SS}	V_{DD}	V_{DDQ}	DQ_B	DQ_B
G	DQ_C	DQ_C	V_{DDQ}	V_{DD}	V_{SS}	V_{SS}	V_{SS}	V_{DD}	V_{DDQ}	DQ_B	DQ_B
H	NC	NC	NC	V_{DD}	V_{SS}	V_{SS}	V_{SS}	V_{DD}	NC	NC	ZZ
J	DQ_D	DQ_D	V_{DDQ}	V_{DD}	V_{SS}	V_{SS}	V_{SS}	V_{DD}	V_{DDQ}	DQ_A	DQ_A
K	DQ_D	DQ_D	V_{DDQ}	V_{DD}	V_{SS}	V_{SS}	V_{SS}	V_{DD}	V_{DDQ}	DQ_A	DQ_A
L	DQ_D	DQ_D	V_{DDQ}	V_{DD}	V_{SS}	V_{SS}	V_{SS}	V_{DD}	V_{DDQ}	DQ_A	DQ_A
M	DQ_D	DQ_D	V_{DDQ}	V_{DD}	V_{SS}	V_{SS}	V_{SS}	V_{DD}	V_{DDQ}	DQ_A	DQ_A
N	DQP_D	NC	V_{DDQ}	V_{SS}	NC	NC	NC	V_{SS}	V_{DDQ}	NC	DQP_A
P	NC/144M	NC/72M	A	A	TDI	A1	TDO	A	A	A	NC/288M
R	MODE	NC/36M	A	A	TMS	A0	TCK	A	A	A	A

Pin Definitions

Pin	Name	Function
A_0, A_1, A	Input-Synchronous	**Address Inputs used to select one of the address locations.** Sampled at the rising edge of the CLK.
$\overline{BW}_A$, $\overline{BW}_B$, $\overline{BW}_C$, $\overline{BW}_D$	Input-Synchronous	**Byte Write Select Inputs, active LOW.** Qualified with $\overline{WE}$ to conduct byte writes to the SRAM. Sampled on the rising edge of CLK. $\overline{BW}_A$ controls DQ_A and DQP_A, $\overline{BW}_B$ controls DQ_B and DQP_B, $\overline{BW}_C$ controls DQ_C and DQP_C, $\overline{BW}_D$ controls DQ_D and DQP_D.
$\overline{WE}$	Input-Synchronous	**Write Enable Input, active LOW.** Sampled on the rising edge of CLK if $\overline{CEN}$ is active LOW. This signal must be asserted LOW to initiate a write sequence.
ADV/$\overline{LD}$	Input-Synchronous	**Advance/Load Input used to advance the on-chip address counter or load a new address.** When HIGH (and $\overline{CEN}$ is asserted LOW) the internal burst counter is advanced. When LOW, a new address can be loaded into the device for an access. After being deselected, ADV/$\overline{LD}$ should be driven LOW in order to load a new address.
CLK	Input Clock	**Clock Input.** Used to capture all synchronous inputs to the device. CLK is qualified with $\overline{CEN}$. CLK is only recognized if $\overline{CEN}$ is active LOW.
$\overline{CE}_1$	Input-Synchronous	**Chip Enable 1 Input, active LOW.** Sampled on the rising edge of CLK. Used in conjunction with CE_2 and $\overline{CE}_3$ to select/deselect the device.
CE_2	Input-Synchronous	**Chip Enable 2 Input, active HIGH.** Sampled on the rising edge of CLK. Used in conjunction with $\overline{CE}_1$ and $\overline{CE}_3$ to select/deselect the device.
$\overline{CE}_3$	Input-Synchronous	**Chip Enable 3 Input, active LOW.** Sampled on the rising edge of CLK. Used in conjunction with $\overline{CE}_1$ and CE_2 to select/deselect the device
$\overline{OE}$	Input-Asynchronous	**Output Enable, active LOW.** Combine with the synchronous logic block inside the device to control the direction of the I/O pins. When LOW, the I/O pins are allowed to behave as outputs. When deasserted HIGH, I/O pins are tri-stated, and act as input data pins. $\overline{OE}$ is masked during the data portion of a write sequence, during the first clock when emerging from deselected state and when the device has been deselected.
$\overline{CEN}$	Input-Synchronous	**Clock Enable Input, active LOW.** When asserted LOW the clock signal is recognized by the SRAM. When deasserted HIGH the clock signal is masked. Since deasserting $\overline{CEN}$ does not deselect the device, $\overline{CEN}$ can be used to extend the previous cycle when required.

Figure 2. Terminal connections. – continued.

Pin Definitions – continued.

Pin	Name	Function
DQs	I/O- Synchronous	**Bidirectional Data I/O lines.** As inputs, they feed into an on-chip data register that is triggered by the rising edge of CLK. As outputs, they deliver the data contained in the memory location specified by $A_{[17:0]}$ during the previous clock rise of the read cycle. The direction of the pins is controlled by $\overline{OE}$ and the internal control logic. When $\overline{OE}$ is asserted LOW, the pins can behave as outputs. When HIGH, DQ_A – DQ_D are placed in a tri-state condition. The outputs are automatically tri-stated during the data portion of a write sequence, during the first clock when emerging from a deselected state, and when the device is deselected, regardless of the state of $\overline{OE}$.
DQP_X	I/O- Synchronous	**Bidirectional DataParity I/O lines.** Functionally, these signals are identical to DQ_S. During write sequences, DQP_A is controlled by $\overline{BW}_A$, DQP_B is controlled by $\overline{BW}_B$, DQP_C is controlled by $\overline{BW}_C$ and DQP_D is controlled by $\overline{BW}_D$
MODE	Input Strap Pin	**Mode Input.** Selects the burst order of the device. Tied HIGH selects the interleaved burst order. Pulled LOW selects the linear burst order. MODE should not change states during operation. When left floating MODE will default HIGH, to an interleaved burst order.
TDO	JTAG serial output Synchronous	**Serial data-out to the JTAG circuit.** Delivers data on the negative edge of TCK
TDI	JTAG serial input Synchronous	**Serial data-in to the JTAG circuit.** Sampled on the rising edge of TCK.
TMS	Test Mode Select Synchronous	**This pin controls the Test Access Port state machine.** Sampled on the rising edge of TCK.
TCK	JTAG - Clock	**Clock input to the JTAG circuitry.**
V_{DD}	Power Supply	**Power Supply Inputs to the core of the device.**
V_{SS}	Ground	**Ground for the device.**
V_{DDQ}	I/O Power Supply	**Power Supply for the I/O circuitry.**
ZZ	Input- Asynchronous	**ZZ "sleep" Input.** This active HIGH input places the device in a non-time critical "sleep" condition with data integrity preserved. During normal operation, this pin has to be LOW or left floating. ZZ pins has an internal pull-down.
NC	---	**No Connects.** This pin is not connected to the die.
NC/(36M, 72M, 144M, 288M, 576M, 1G)	---	**These pins are not connected.** They will be used for expansion to the 36M, 72M, 144M, 288M, 576M and 1G densities.

FIGURE 2. Terminal connections. - continued

Truth Table 1/ 2/ 3/ 4/ 5/ 6/ 7/

Operation	Address Used	$\overline{CE}$	ZZ	ADV/$\overline{LD}$	$\overline{WE}$	$\overline{BW}_X$	$\overline{OE}$	$\overline{CEN}$	CLK	DQ
Deselect Cycle	None	H	L	L	X	X	X	L	L-H	Tri-State
Continue Deselect Cycle	None	X	L	H	X	X	X	L	L-H	Tri-State
Read Cycle (Begin Burst)	External	L	L	L	H	X	L	L	L-H	Data Out (Q)
Read Cycle (Continue Burst)	Next	X	L	H	X	X	L	L	L-H	Data Out (Q)
NOP/Dummy Read (Begin Burst)	External	L	L	L	H	X	H	L	L-H	Tri-State
Dummy Read (Continue Burst)	Next	X	L	H	X	X	H	L	L-H	Tri-State
Write Cycle (Begin Burst)	External	L	L	L	L	L	X	L	L-H	Data In (D)
Write Cycle (Continue Burst)	Next	X	L	H	X	L	X	L	L-H	Data In (D)
NOP/Write Abort (Begin Burst)	None	L	L	L	L	H	X	L	L-H	Tri-State
Write Abort (Continue Burst)	Next	X	L	H	X	H	X	L	L-H	Tri-State
Ignore Clock Edge (Stall)	Current	X	L	X	X	X	X	H	L-H	---
Sleep Mode	None	X	H	X	X	X	X	X	X	Tri-State

Partial Truth Table for Read/Write 1/ 2/ 3/ 8/

Function	$\overline{WE}$	$\overline{BW}_D$	$\overline{BW}_C$	$\overline{BW}_B$	$\overline{BW}_A$
Read	H	X	X	X	X
Write – No bytes written	L	H	H	H	H
Write Byte A - (DQ_A and DQP_A)	L	H	H	H	L
Write Byte B - (DQ_B and DQP_B)	L	H	H	L	H
Write Bytes B, A	L	H	H	L	L
Write Byte C- (DQ_C and DQP_C)	L	H	L	H	H
Write Bytes C, A	L	H	L	H	L
Write Bytes C, B	L	H	L	L	H
Write Bytes C, B, A	L	H	L	L	L
Write Byte D – (DQ_D and DQP_D)	L	L	H	H	H
Write Bytes D, A	L	L	H	H	L
Write Bytes D, B	L	L	H	L	H
Write Bytes D, B, A	L	L	H	L	L
Write Bytes D, C	L	L	L	H	H
Write Bytes D, C, A	L	L	L	H	L
Write Bytes D, C, B	L	L	L	L	H
Write All Bytes	L	L	L	L	L

Notes:

1/ X = "Don't Care." H = Logic HIGH, L = Logic LOW, $\overline{CE}$ stands for ALL Chip Enables active. $\overline{BW}_X$ = L signifies at least one Byte Write Select is active, $\overline{BW}_X$ = Valid signifies that the desired byte write selects are asserted, see Truth Table for details.

2/ Write is defined by $\overline{WE}$ and $\overline{BW}_X$. See Truth Table for details.

3/ When a write cycle is detected, all I/Os are tri-stated, even during byte writes.

4/ The DQ and DQP pins are controlled by the current cycle and the $\overline{OE}$ signal.

5/ $\overline{CEN}$ = H inserts wait states.

6/ Device will power-up deselected and the I/Os in a tri-state condition regardless of $\overline{OE}$.

7/ $\overline{OE}$ is asynchronous and is not sampled with the clock rise. It is masked internally during write cycles. During a read cycle DQ_S and DQP_X = Three-state when $\overline{OE}$ is inactive or when the device is deselected, and DQ_S = data when $\overline{OE}$ is active.

8/ Table only lists a partial listing of the byte write combinations. Any combination of $\overline{BW}_X$ is valid. Appropriate write will be done based on which byte write is active.

Figure 3. Truth table and device operations.

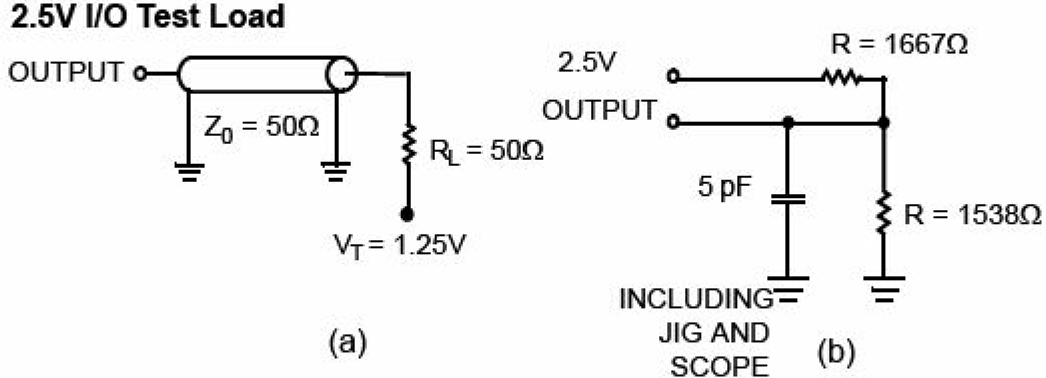
Interleaved Burst Address Table
(MODE = Floating or V_{DD})

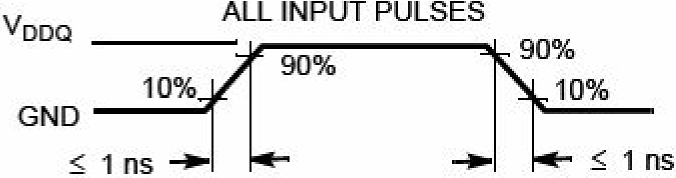
First Address A_1, A_0	Second Address A_1, A_0	Third Address A_1, A_0	Fourth Address A_1, A_0
00	01	10	11
01	00	11	10
10	11	00	01
11	10	01	00

Linear Burst Address Table
(MODE = GND)

First Address A_1, A_0	Second Address A_1, A_0	Third Address A_1, A_0	Fourth Address A_1, A_0
00	01	10	11
01	10	11	00
10	11	00	01
11	00	01	10

Figure 3. Truth table and device operations.–continued.





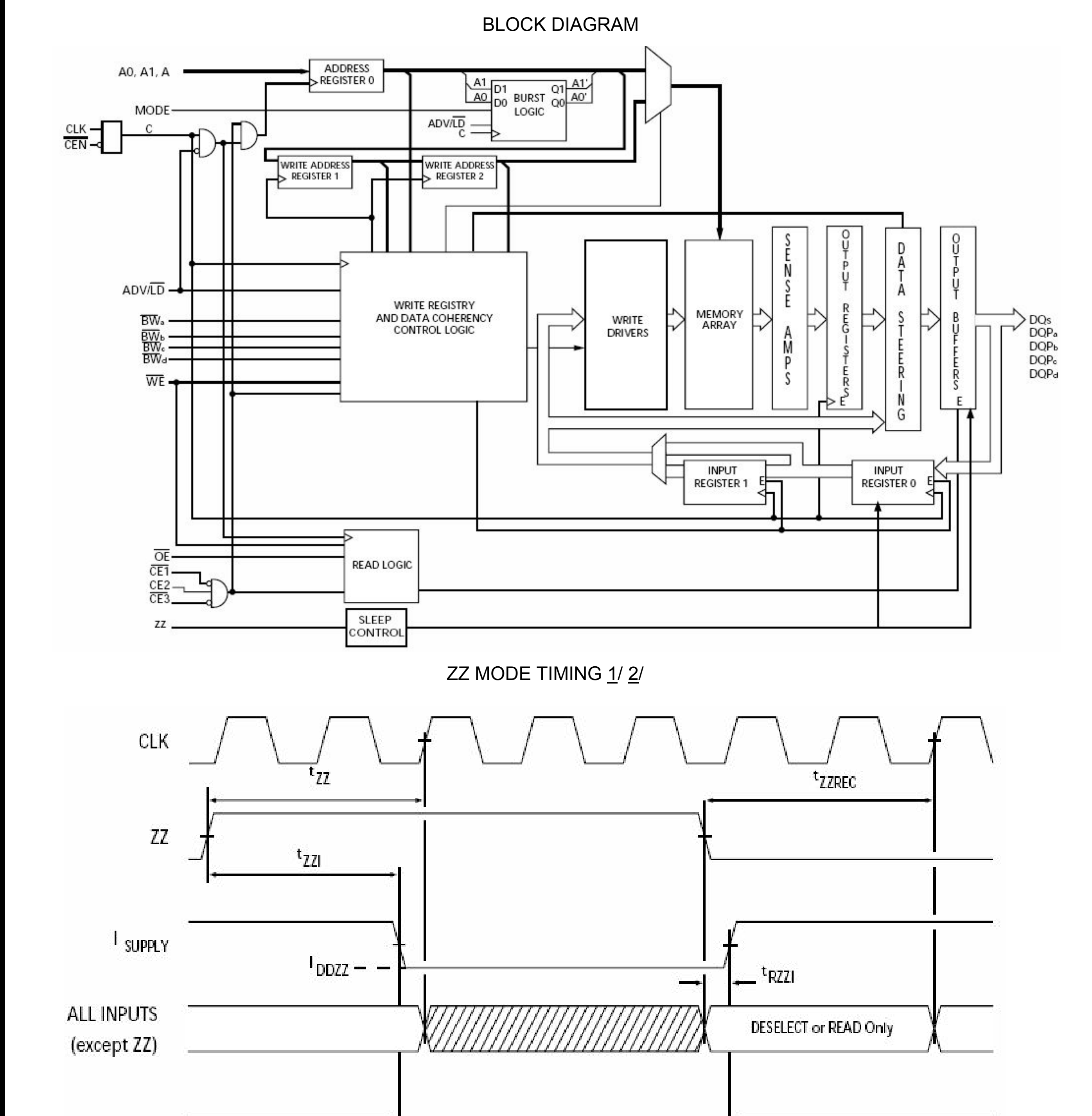
NOTES:

1. Use these output load circuits or equivalent for testing.
2. Capacitive load consists of all components of the test environment, including jig and scope.

Figure 4. Output load circuits.

BLOCK DIAGRAM

ZZ MODE TIMING 1/ 2/



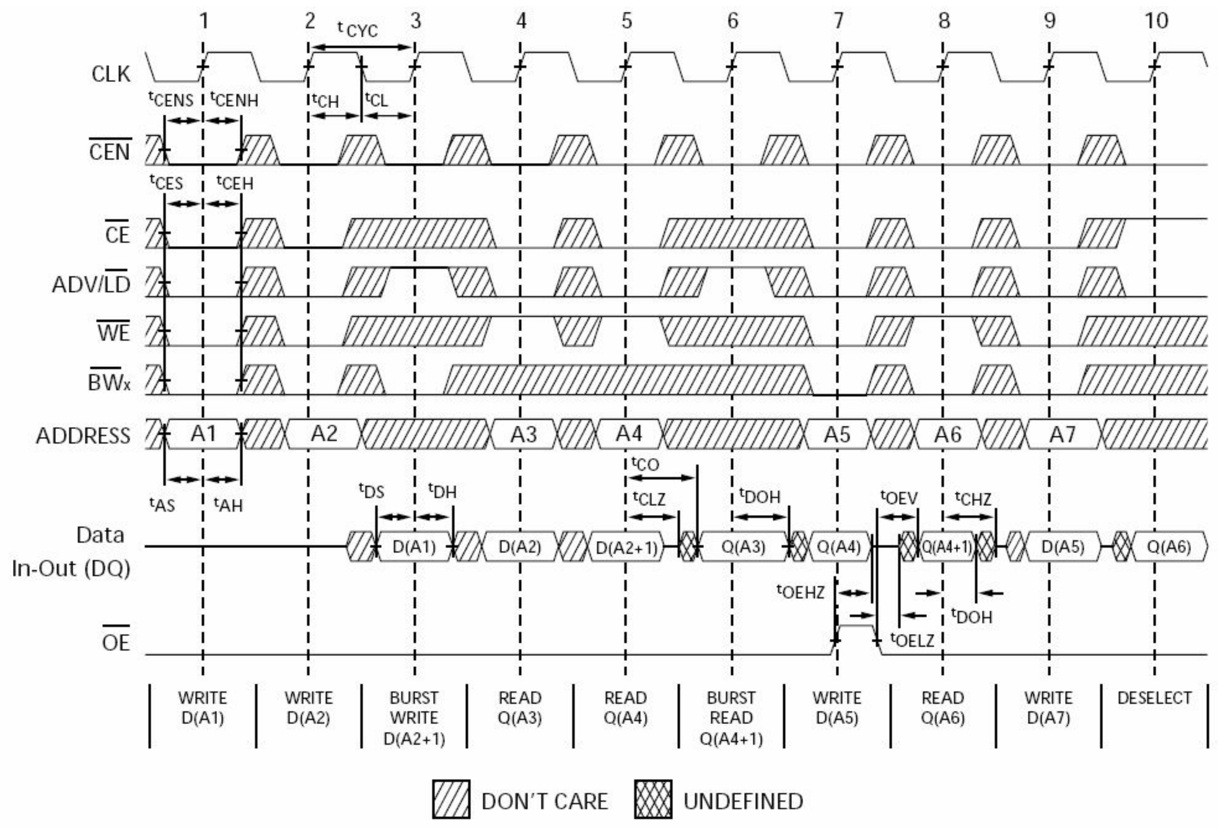
NOTES:

1/ Device must be deselected when entering ZZ mode. See the Truth Table for all possible signal conditions to deselect the device.

2/ I/Os are in high-Z when exiting ZZ sleep mode.

Figure 5. Timing waveforms.

READ/WRITE CYCLE TIMING 3/ 4/ 5/



NOTES:

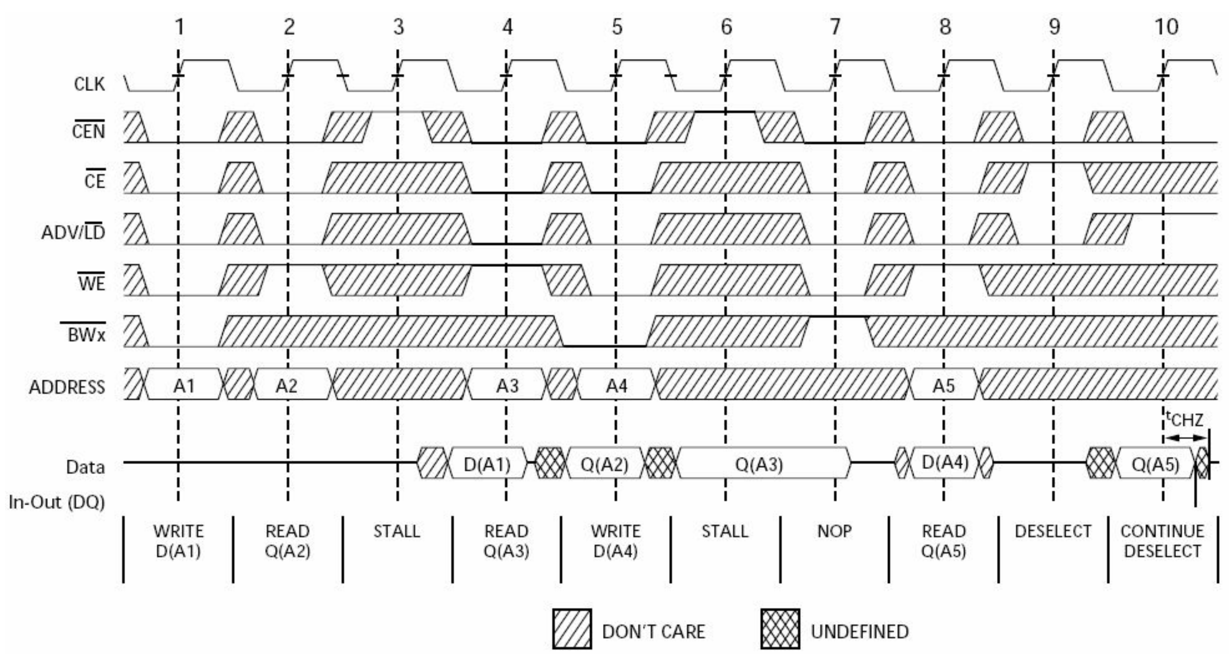
3/ For this waveform ZZ is tied LOW.

4/ On this diagram, when $\overline{CE}$ is LOW, $\overline{CE}_1$ is LOW, CE_2 is HIGH and $\overline{CE}_3$ is LOW. When $\overline{CE}$ is HIGH, $\overline{CE}_1$ is HIGH or CE_2 is LOW or $\overline{CE}_3$ is HIGH.

5/ Order of the Burst sequence is determined by the status of the MODE (0 = Linear, 1 = Interleaved). Burst operations are optional.

Figure 5. Timing waveforms - continued

NOP, STALL AND DESELECT CYCLE TIMING 3/ 4/ 6/



NOTES:

6/ The Ignore Clock Edge or Stall cycle (Clock 3) illustrated $\overline{\text{CEN}}$ being used to create a pause. A write is not preformed during this cycle.

Figure 5. Timing waveforms - continued

TABLE IIA. Electrical test requirements. 1/ 2/ 3/ 4/ 5/ 6/ 7/ 8/

Line No.	Test Requirements	Subgroups (In accordance with MIL-PRF-38535, Table III)		
		Device Class N	Device Class Q	Device Class V
1	Interim electrical parameters (See 4.2)			1, 7, 9
2	Static Burn-In I Method 1015	Not Required	Not required	Required
3	Same as Line 1			1*, 7* Δ
4	Dynamic Burn-In (Method 1015)	Required	Required	Required
5	Same as Line 1			1*, 7* Δ
6	Final Electrical Parameters	1*, 2, 3, 7*, 8A, 8B, 9, 10, 11	1*, 2, 3, 7*, 8A, 8B, 9, 10, 11	1*, 2, 3, 7*, 8A, 8B, 9, 10, 11
7	Group A Test Requirements	1, 2, 3, 4**, 7, 8A, 8B, 9, 10, 11	1, 2, 3, 4**, 7,8A, 8B, 9, 10, 11	1, 2, 3, 4**, 7,8A, 8B, 9, 10, 11
8	Group C End-Point Electrical Parameters	2, 3, 7, 8A, 8B	2, 3,7, 8A, 8B	1, 2, 3, 7, 8A, 8B, 9, 10, 11 Δ
9	Group D End-Point Electrical Parameters	2, 3, 8A, 8B	2, 3, 8A, 8B	2, 3, 8A, 8B
10	Group E End-Point Electrical Parameters	1, 7, 9	1, 7, 9	1, 7, 9

1/ Blank spaces indicate tests are not applicable.
2/ Any or all subgroups may be combined when using high-speed testers.
3/ Subgroups 7 and 8 functional tests shall verify the truth table.
4/ * indicates PDA applies to subgroup 1 and 7.
5/ ** see 4.4.1e.
6/ Δ indicates delta limit (see table IIB) shall be required where specified, and the delta values shall be computed with reference to the previous interim electrical parameters (see line 1).
7/ See 4.4.1d.
8/ Group A testing is not required if the requirements of MIL-PRF-38535 appendix B paragraph (B.4.2.a) have been accomplished.

TABLE IIB. Delta limits at +25°C.

Parameter 1/	All device types
I_{SB2}, I_{SB4}	$\pm$10% of specified value in table I
I_X, I_{OZ}	$\pm$10% of specified value in table I

1/ The above parameter shall be recorded before and after the required burn-in and life tests to determine the delta.

4. VERIFICATION

4.1 Sampling and inspection. For device classes N, Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

4.2 Screening. For device classes N, Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection.

4.2.1 Additional criteria for device classes N, Q and V.

a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.

b. Interim and final electrical test parameters shall be as specified in table IIA herein.

c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.

4.3 Qualification inspection for device classes N, Q and V. Qualification inspection for device classes N, Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 Conformance inspection. Technology conformance inspection for classes N, Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections and as specified herein.

4.4.1 Group A inspection.

a. Tests shall be as specified in table IIA herein. Group A testing is not required if all tests have been performed during final electrical of the 100% Screening test. See footnote 8/ for table IIA.

b. Subgroups 5 and 6 of table I of method 5005 of MIL-STD-883 shall be omitted.

c. O/V (latch-up) tests shall be measured only for initial qualification and after any design or process changes which may affect the performance of the device. For device classes N, Q and V, the procedures and circuits shall be under the control of the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the preparing activity or acquiring activity upon request. Testing shall be on all pins, on five devices with zero failures. Latch-up test shall be considered destructive. Information contained in JEDEC Standard EIA/JESD78 may be used for reference.

d. Subgroup 4 (C_{IN} and C_{OUT} measurements) shall be measured only for initial qualification and after any process or design changes which may affect input or output capacitance. Capacitance shall be measured between the designated terminal and GND at a frequency of 1 MHz. Sample size is 5 devices with no failures, and all input and output terminals tested.

4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.2.1 Additional criteria for device classes N, Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.

4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.4 Group E inspection. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).

a. End-point electrical parameters shall be as specified in table IIA herein.

b. For device classes N, Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at T_A = +25ºC ±5ºC, after exposure, to the subgroups specified in table IIA herein.

c. When specified in the purchase order or contract, a copy of the RHA delta limits shall be supplied.

4.5 Delta measurements for device class V. Delta measurements, as specified in table IIA, shall be made and recorded before and after the required burn-in screens and steady-state life tests to determine delta compliance. The electrical parameters to be measured, with associated delta limits are listed in table IIB. The device manufacturer may, at his option, either perform delta measurements or within 24 hours after burn-in perform final electrical parameter tests, subgroups 1, 7, and 9.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes N, Q and V.

5.2 Special Class N handling. Class N device is rated as a Moisture Sensitivity Level 3 part when tested per J-STD-020A. Device will be baked and dry packed when shipped from the manufacturer. Device will require a 125°C dry bake for 24 hours prior to installation if prolonged exposure on normal factory floor of the end user has occurred.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor prepared specification or drawing.

6.2 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.3 Record of users. Military and industrial users should inform Defense Supply Center Columbus (DSCC) when a system application requires configuration control and which SMD's are applicable to that system. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0544.

6.4 Comments. Comments on this drawing should be directed to DSCC-VA , Columbus, Ohio 43216-5000, or telephone (614) 692-0547.

6.5 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

6.5.1 Timing limits. The table of timing values shows either a minimum or a maximum limit for each parameter. Input requirements are specified from the external system point of view. Thus, address setup time is shown as a minimum since the

system must supply at least that much time (even though most devices do not require it). On the other hand, responses from the memory are specified from the device point of view. Thus, the access time is shown as a maximum since the device never provides data later than that time.

6.5.2 Waveforms.

Waveform symbol	Input	Output
	MUST BE VALID	WILL BE VALID
	CHANGE FROM H TO L	WILL CHANGE FROM H TO L
	CHANGE FROM L TO H	WILL CHANGE FROM L TO H
	DON'T CARE ANY CHANGE PERMITTED	CHANGING STATE UNKNOWN
		HIGH IMPEDANCE

6.6 Sources of supply.

6.6.1 Sources of supply for device classes N, Q and V. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DSCC-VA and have agreed to this drawing.

STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 09-XX-XX

Approved sources of supply for SMD 5962-08SMD are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535.

Standard microcircuit drawing PIN 1/	Vendor CAGE number	Vendor similar PIN 2/
5962-0823601NXA	6S055	DPA1370DV2525003A
5962-0823602NXA	6S055	DPA1370DV2520003A
5962-0823603NXA	6S055	DPA1370DV2516703A
5962-0823601NYA	6S055	DPA1370DV2525004A
5962-0823602NYA	6S055	DPA1370DV2520004A
5962-0823603NYA	6S055	DPA1370DV2516704A
5962-0823601NZA	6S055	DPA1370DV2525005A
5962-0823602NZA	6S055	DPA1370DV2520005A
5962-0823603NZA	6S055	DPA1370DV2516705A

1/ The lead finish shown for each PIN is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.

2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number	Vendor name and address
6S055	DPA Components International 2251 Ward Avenue Simi Valley, CA 93065

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.